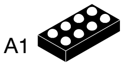
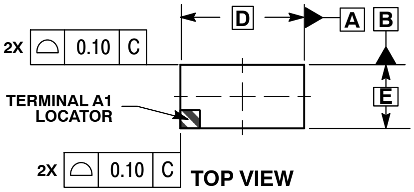
8 PIN FLIP−CHIP, 2.05x1.05, 0.5P

CASE 766AE
ISSUE C

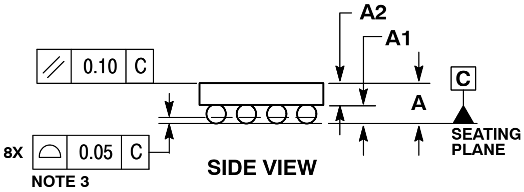
DATE 06 NOV 2006



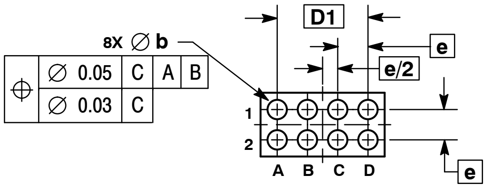
SCALE 4:1



TOP VIEW



SIDE VIEW



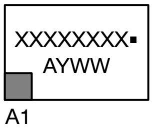
BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS	
DIM	**MIN**	**MAX**
A	---	0.655
A1	0.210	0.270
A2	0.335	0.385
b	0.290	0.340
D	2.050 BSC	
D1	1.500 BSC	
E	1.050 BSC	
e	0.500 BSC	

GENERIC MARKING DIAGRAM*



XXXXXXXX = Specific Device Code
▪ = Pb−Free Device
A = Assembly Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present.

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